

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-89 (Canceled)

Claim 90 (New): An electronic component comprising:

a substrate including a conductive area; and

a resilient, conductive contact structure comprising a base portion electrically coupled to the conductive area of the substrate, a tip portion displaced away from the substrate and the conductive area, and a beam portion between the base portion and the tip portion,

wherein a length of the beam portion extends from the base portion to the tip portion, and a width of the beam portion decreases along the length from the base portion to the tip portion.

Claim 91 (New): The electronic component of claim 90 further comprising:

a connecting layer coupling the conductive area to internal circuitry within the electronic component;

a passivation layer disposed on a surface of the substrate, the passivation layer having an opening at the conductive area of the substrate; and

at least one electrically conductive layer disposed on the passivation layer and on the conductive area of the substrate,

wherein the base portion of the contact structure is electrically coupled through the at least one electrically conductive layer to the conductive area of the substrate.

Claim 92 (New): The electronic component of claim 91, wherein the conductive area comprises a terminal.

Claim 93 (New): The electronic component of claim 91 further comprising a terminal on the substrate, the terminal being electrically connected to the conductive area.

Claim 94 (New): The electronic component of claim 91, wherein the tip portion comprises a pointed end.

Claim 95 (New): The electronic component of claim 91, wherein the substrate comprises a semiconductor device.

Claim 96 (New): The electronic component of claim 91, wherein the contact structure comprises a metal layer.

Claim 97 (New): The electronic component of claim 96, wherein the contact structure comprises a plurality of metal layers.

Claim 98 (New): The electronic component of claim 91 further comprising a plurality of the contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

Claim 99 (New): The electronic component of claim 91, wherein the tip portion comprises a beveled peripheral edge.

Claim 100 (New): The electronic component of claim 91, wherein the beam portion comprises a triangular shape.

Claim 101 (New): The electronic component of claim 100, wherein the tip portion comprises a quadrilateral shape.

Claim 102 (New): The electronic component of claim 101, wherein the tip portion comprises a rectangular shape.

Claim 103 (New): The electronic component of claim 91, wherein the length of the beam portion comprises a generally linear slope from the base portion to the tip portion.

Claim 104 (New): An electronics system comprising:

- a first substrate including a conductive area;

- a resilient conductive contact structure comprising a base portion electrically coupled to the conductive area of the first substrate, a tip portion displaced away from the first substrate, and a beam portion between the base portion and the tip portion, wherein a length of the beam portion extends from the base portion to the tip portion, and a width of the beam portion decreases along the length from the base portion to the tip portion; and

- a second substrate including a conductive contact element in physical contact with the contact structure and deflecting the contact structure, the contact structure exerting a force against the contact element due to the resiliency of the contact structure.

Claim 105 (New): The electronics system of claim 104 further comprising:

- a connecting layer coupling the conductive area to internal circuitry within the first substrate;

- a passivation layer disposed on a surface of the first substrate, the passivation layer having an opening at the conductive area of the first substrate; and

- at least one electrically conductive layer disposed on the passivation layer and on the conductive area of the first substrate,

- wherein the contact structure is electrically coupled through the at least one electrically conductive layer to the conductive area of the first substrate.

Claim 106 (New): The electronics system of claim 105, wherein the conductive area comprises a terminal.

Claim 107 (New): The electronics system of claim 105 further comprising a terminal on the first substrate, the terminal being electrically connected to the conductive area.

Claim 108 (New): The electronics system of claim 105, wherein the tip portion comprises a pointed end.

Claim 109 (New): The electronics system of claim 105, wherein the first substrate comprises a semiconductor device.

Claim 110 (New): The electronics system of claim 105, wherein the contact structure comprises a metal layer.

Claim 111 (New): The electronics system of claim 110, wherein the contact structure comprises a plurality of metal layers.

Claim 112 (New): The electronics system of claim 105 further comprising a plurality of the contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

Claim 113 (New): The electronics system of claim 105, wherein the tip portion comprises a beveled peripheral edge.

Claim 114 (New): The electronics system of claim 105, wherein the beam portion comprises a triangular shape.

Claim 115 (New): The electronics system of claim 114, wherein the tip portion comprises a quadrilateral shape.

Claim 116 (New): The electronics system of claim 115, wherein the tip portion comprises a rectangular shape.

Claim 117 (New): The electronics system of claim 105, wherein the length of the beam portion comprises a generally linear slope from the base portion to the tip portion.